



US00D879729S

(12) **United States Design Patent**
Wang et al.(10) **Patent No.:** **US D879,729 S**
(45) **Date of Patent:** **** Mar. 31, 2020**(54) **ELECTRICAL MODULE**(71) Applicants: **Microduino Inc.**, Westlake Village, CA (US); **Meike Technology (Beijing) Ltd.**, Beijing (CN)(72) Inventors: **Zhenshan Wang**, Westlake Village, CA (US); **Jian Hu**, Westlake Village, CA (US); **Kejia Pan**, Westlake Village, CA (US); **Xi Li**, Westlake Village, CA (US); **Bin Feng**, Westlake Village, CA (US)(73) Assignees: **Microduino Inc.**, Westlake Village, CA (US); **Meike Technology (Beijing) Ltd.**, Beijing (CN)(**) Term: **15 Years**(21) Appl. No.: **29/609,504**(22) Filed: **Jun. 30, 2017**(51) LOC (12) Cl. **13-03**(52) U.S. Cl. **D13/182**(58) **Field of Classification Search**USPC D13/182; 257/678, 684, 690, 691; 361/679.01, 713, 728, 736, 760, 761, 772, 361/775, 783, 820; 174/250, 253; 438/15, 25, 26, 51, 55, 63, 64, 106
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43; H01L 2021/00; H01L 2021/02; H01L 2021/04; H01L 21/4814; H01L 21/4846; H01L 21/4871; H01L 21/67144; H01L 23/02; H01L 23/13; H01L 23/14; H01L 23/147; H01L 2924/171; H01L 2924/1711; H01L 2924/1715; H01L 2924/17151; H01L 2924/181; H01L 2924/1811; H01L 2924/1815; H01L 2924/19042; H01L 2924/1905; H01L 23/58; H05B 41/14; H02B 6/4201; G02B 6/4201; G02B 6/4256; G02B 6/4257; G02B 6/4261; G02B 6/4262; G02B

6/428; G02B 6/4281; H05K 1/18; H05K 1/181; H05K 1/182; H05K 1/026

See application file for complete search history.

(56)

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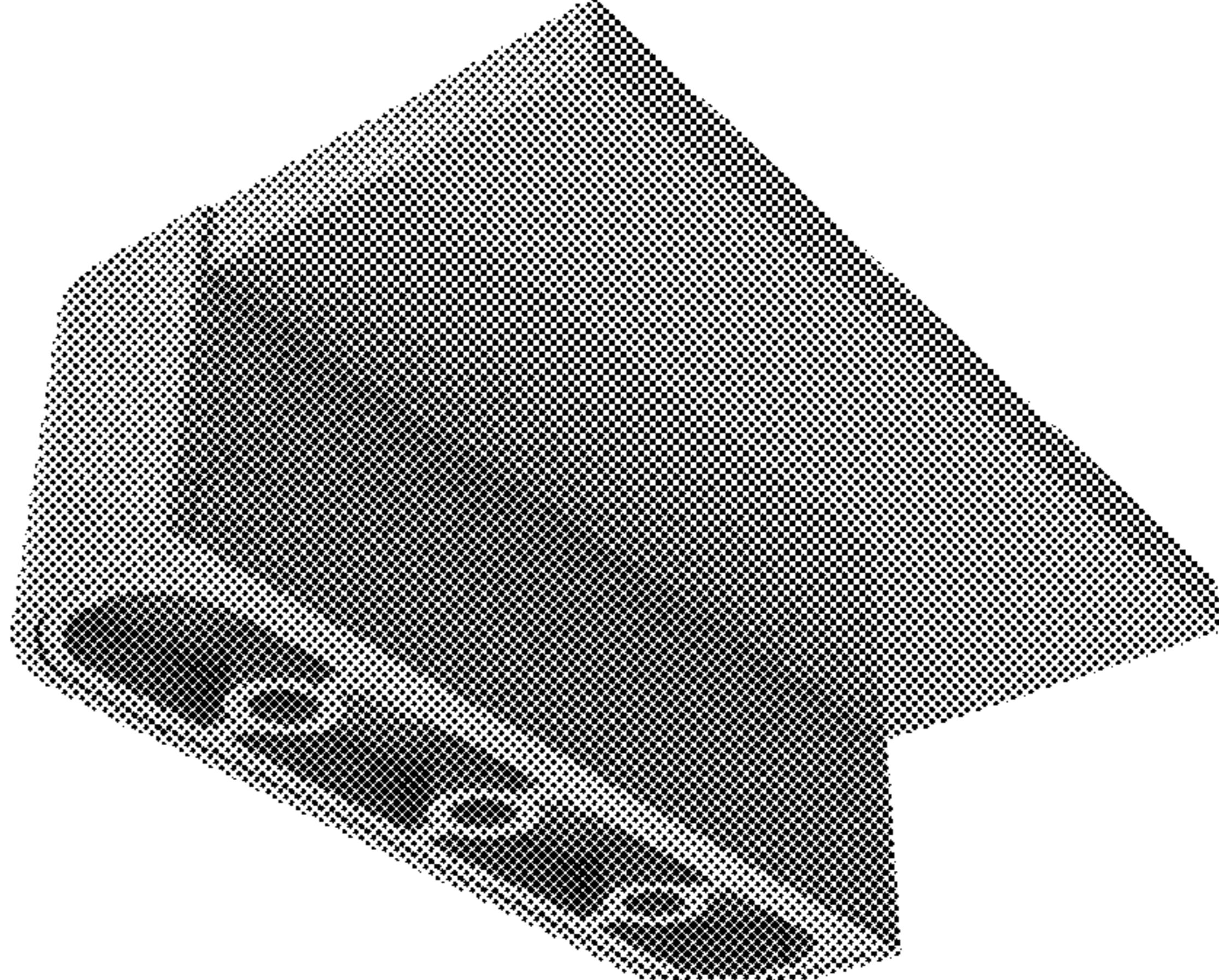
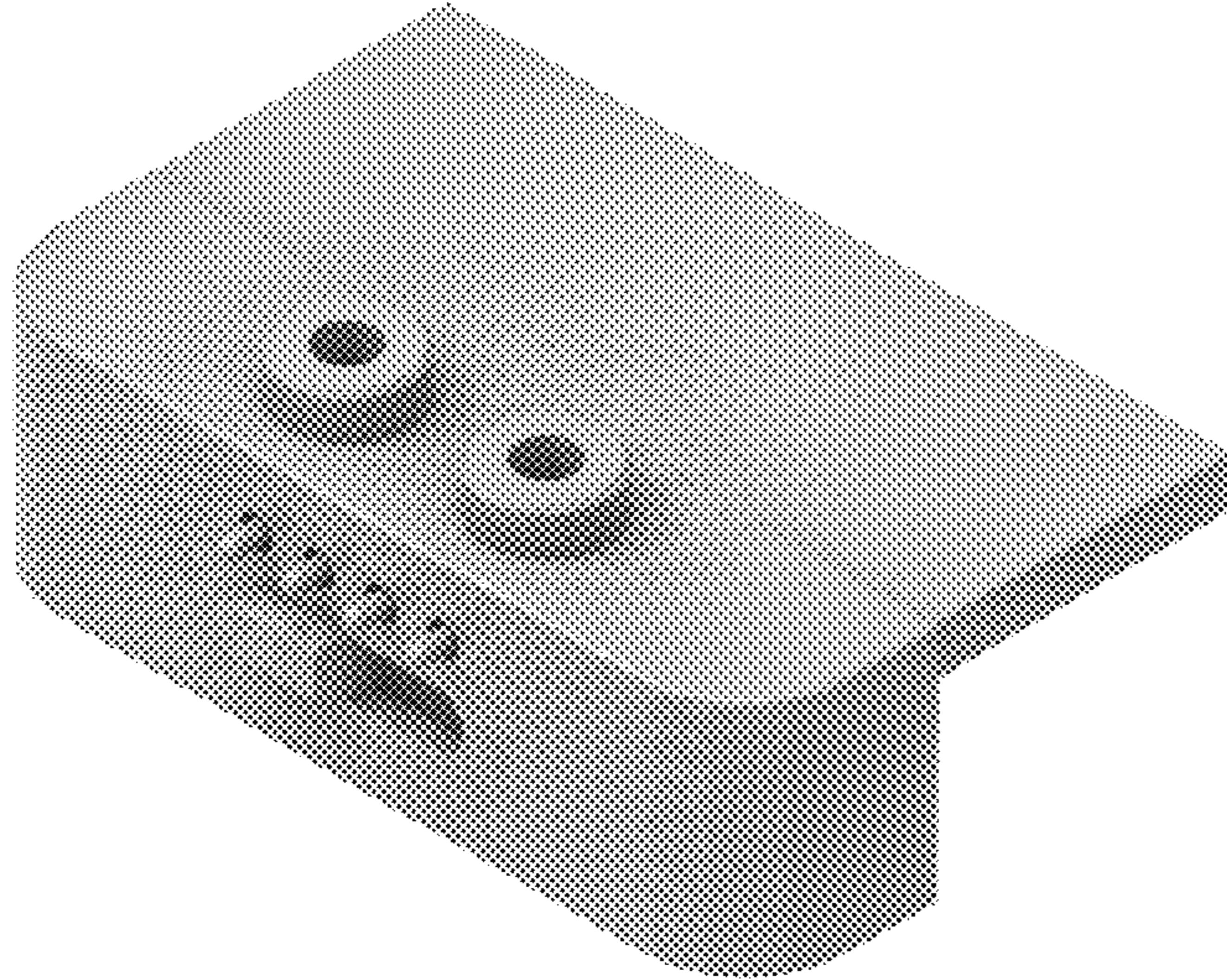
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Primary Examiner — Elizabeth J Oswecki*(74) Attorney, Agent, or Firm* — Anova Law Group, PLLC

(57)

CLAIM

The ornamental design for an electrical module, as shown and described.

DESCRIPTIONFIG. 1 is a front perspective view of an electrical module, showing our new design;
FIG. 2 is a front view thereof;
FIG. 3 is a back view thereof;
FIG. 4 is a left side view thereof;
FIG. 5 is a right side view thereof;
FIG. 6 is a top view thereof;
FIG. 7 is a bottom view thereof; and,
FIG. 8 is a back perspective view thereof.**1 Claim, 4 Drawing Sheets**

(56)

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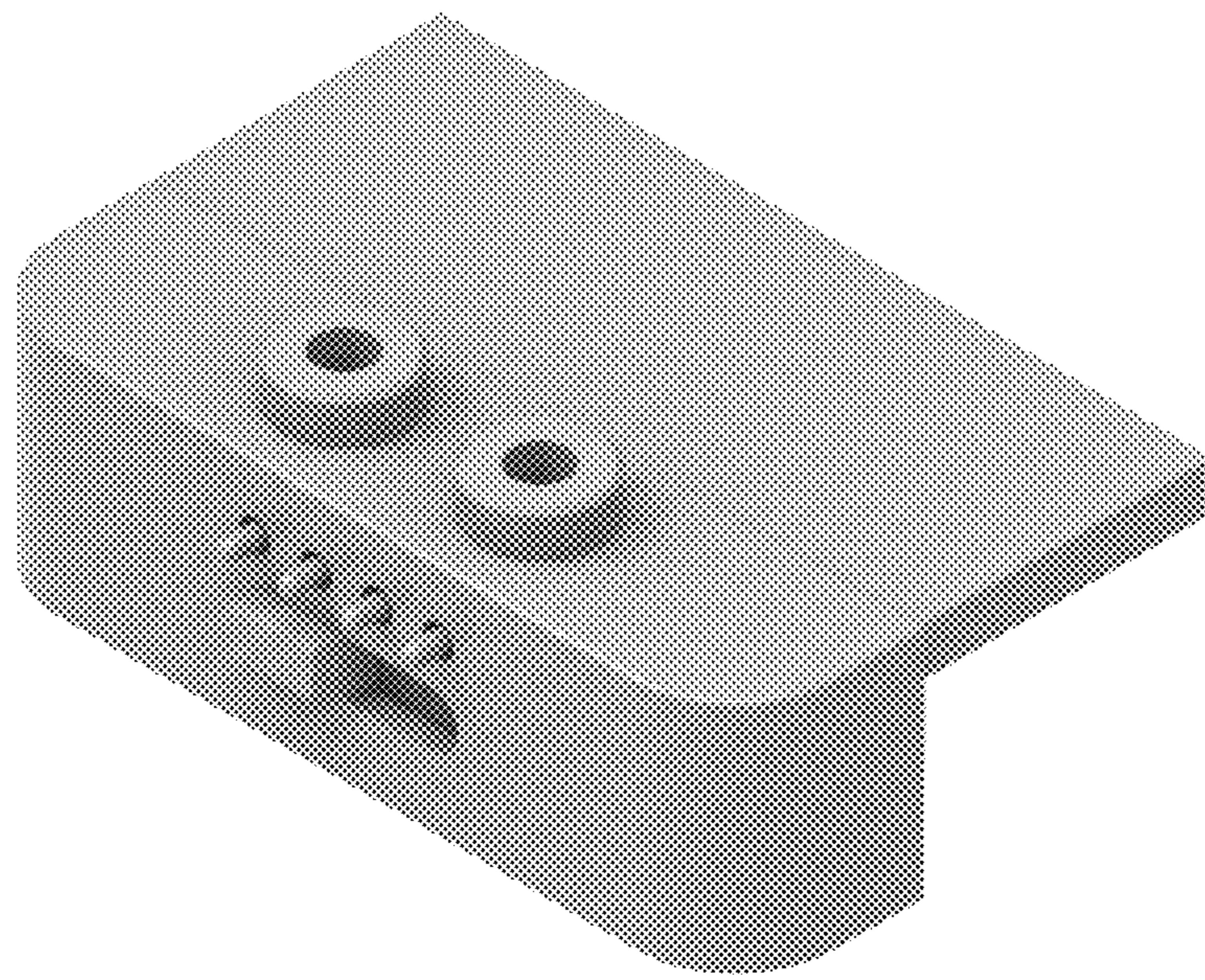


FIG. 1

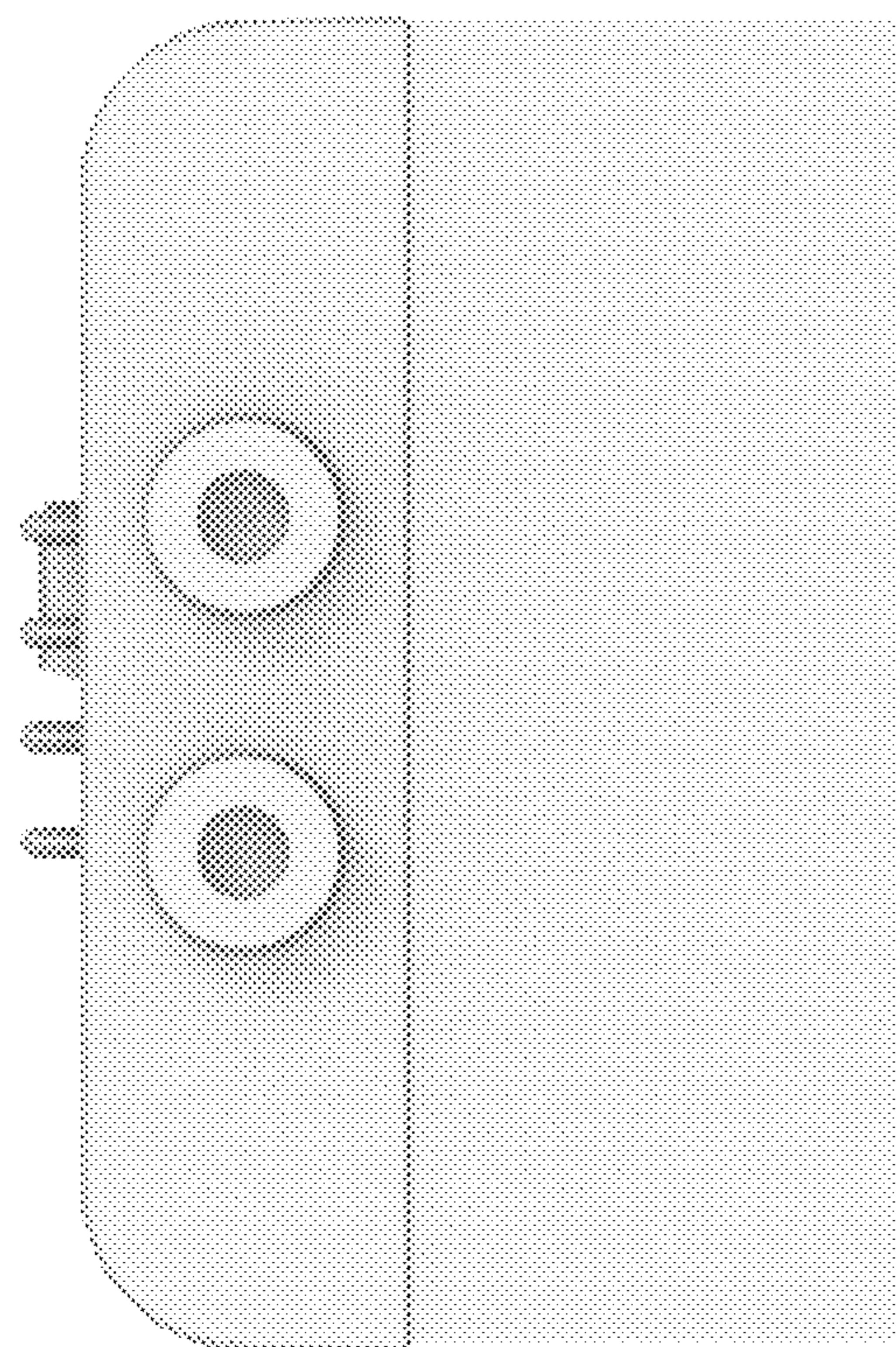


FIG. 2

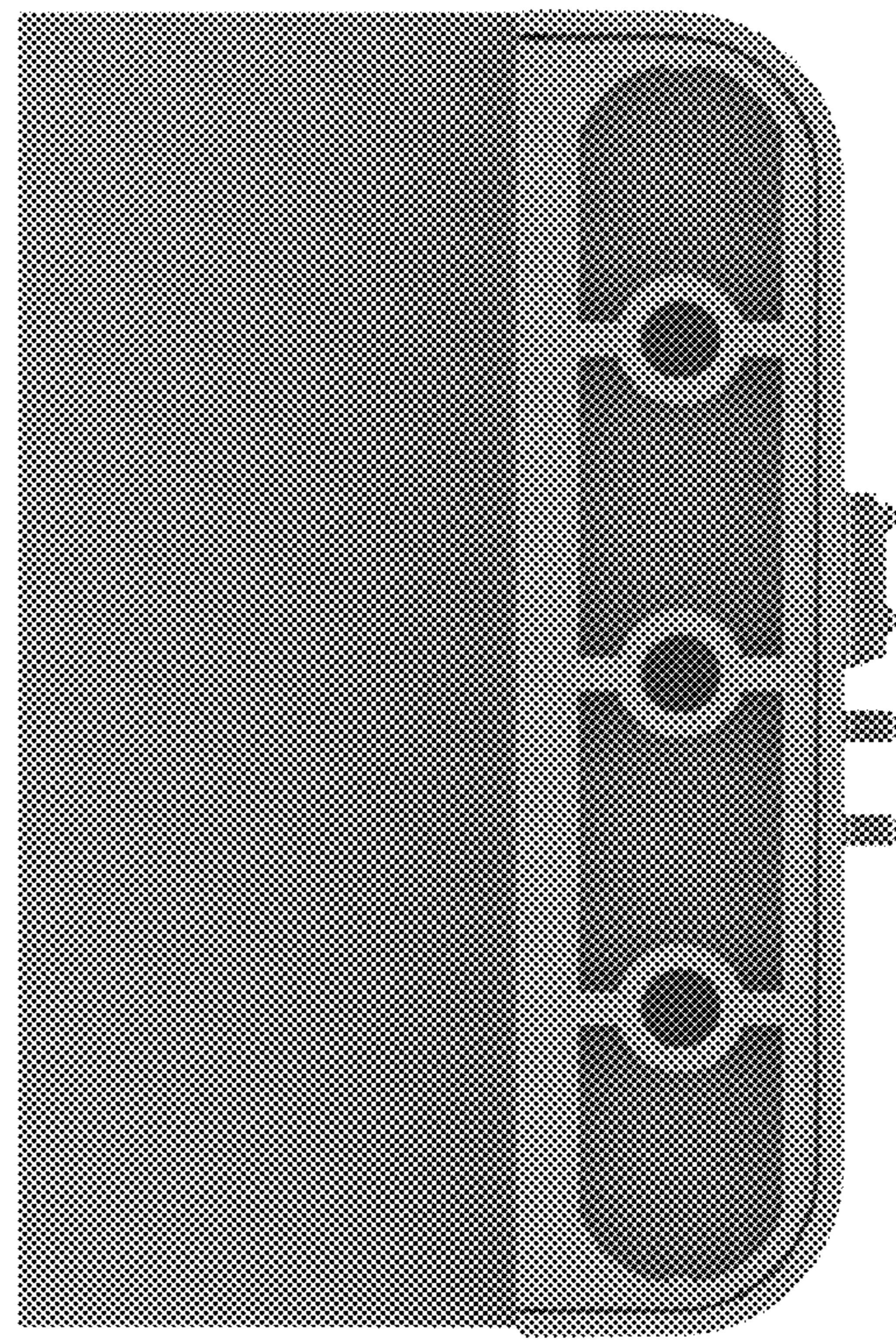


FIG. 3

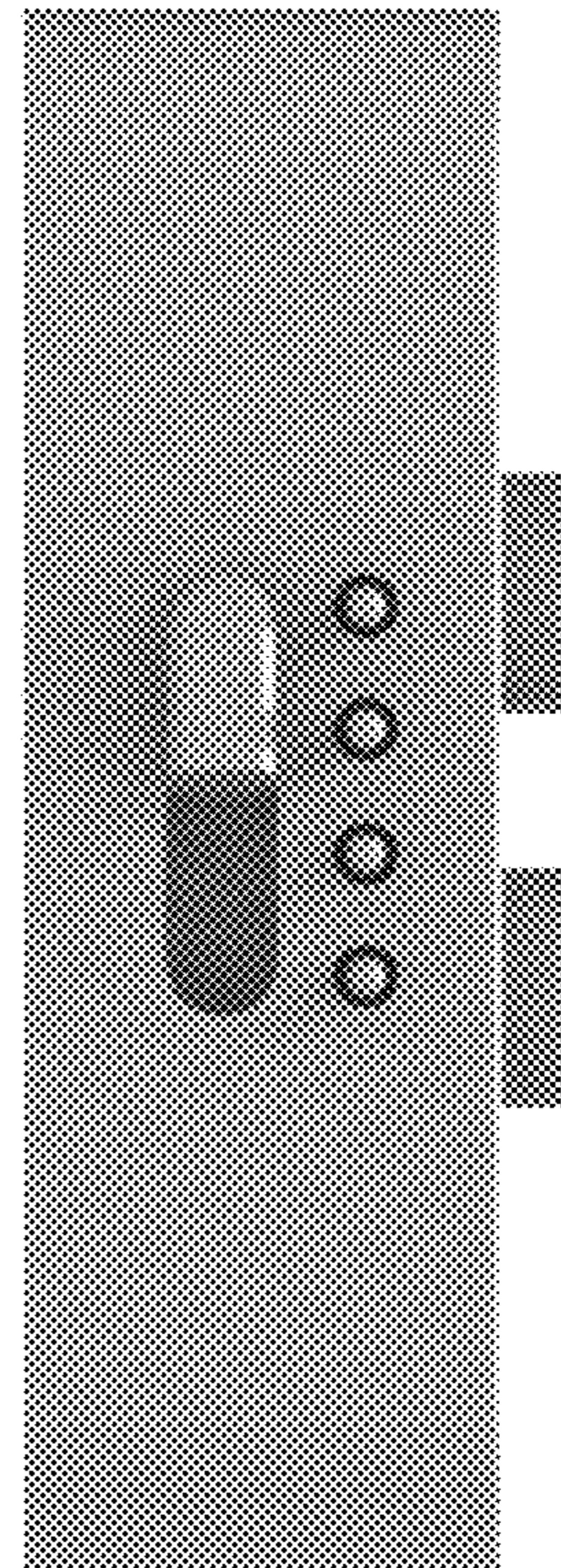


FIG. 4

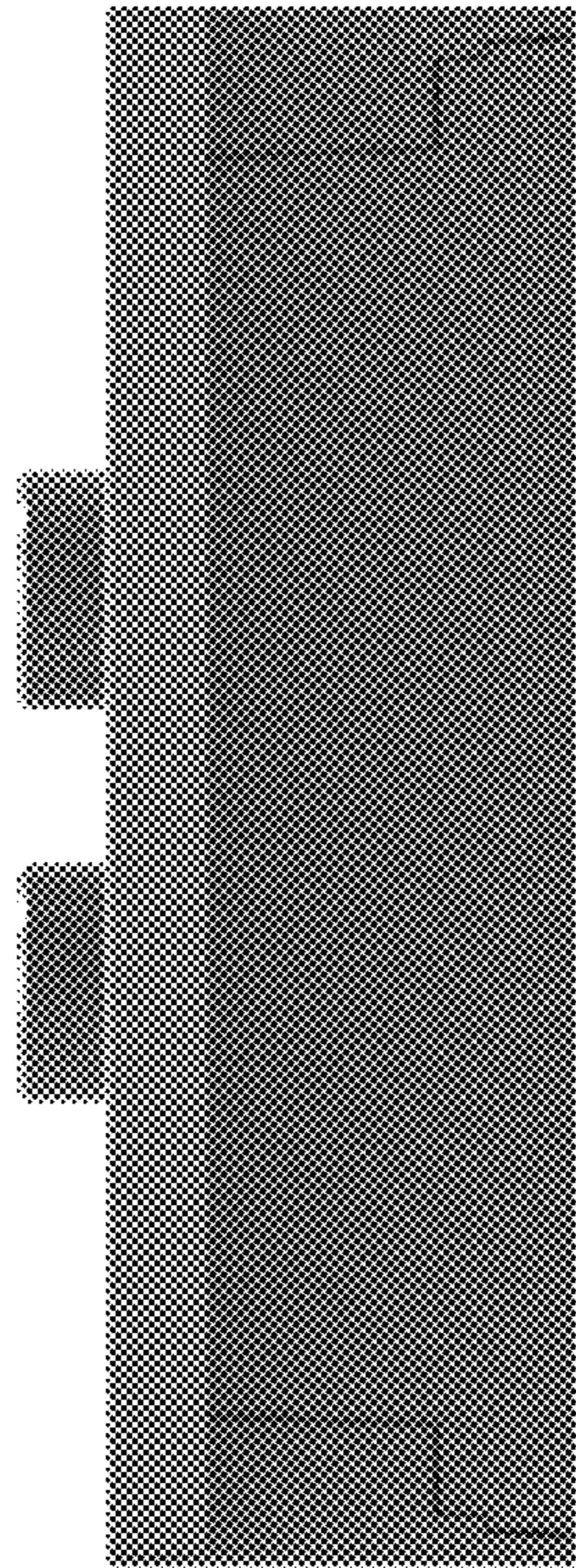


FIG. 5

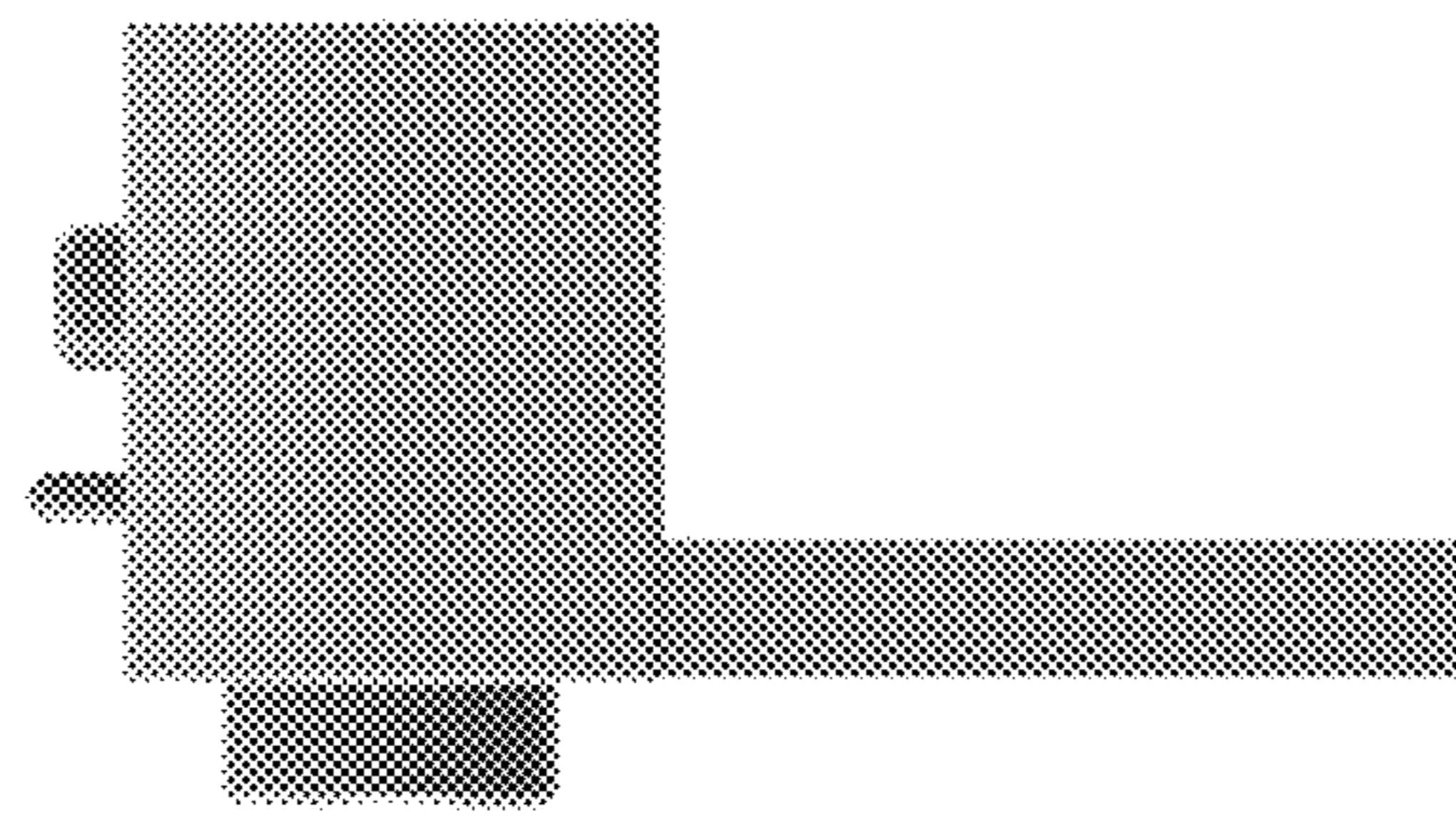


FIG. 6

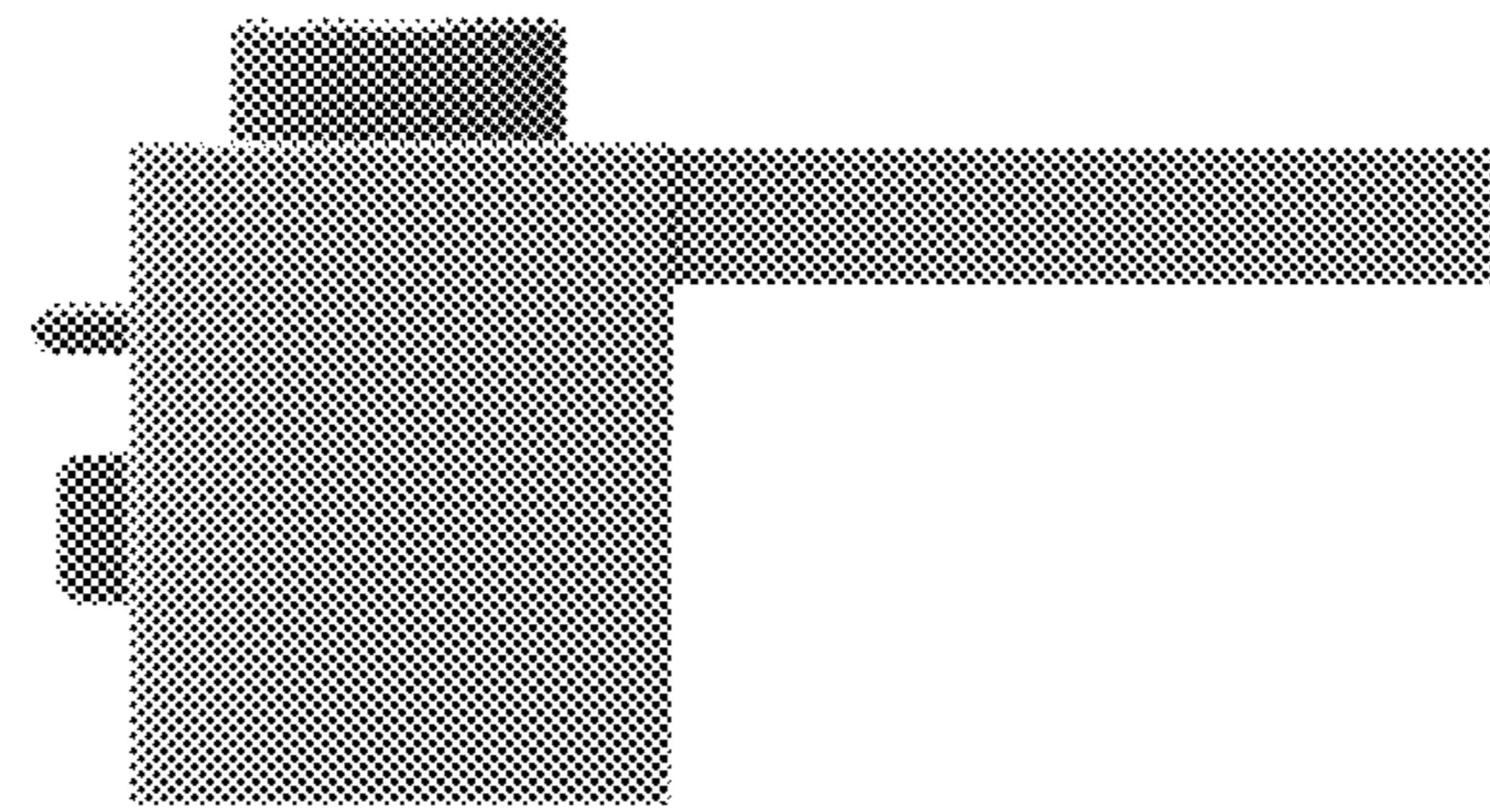


FIG. 7

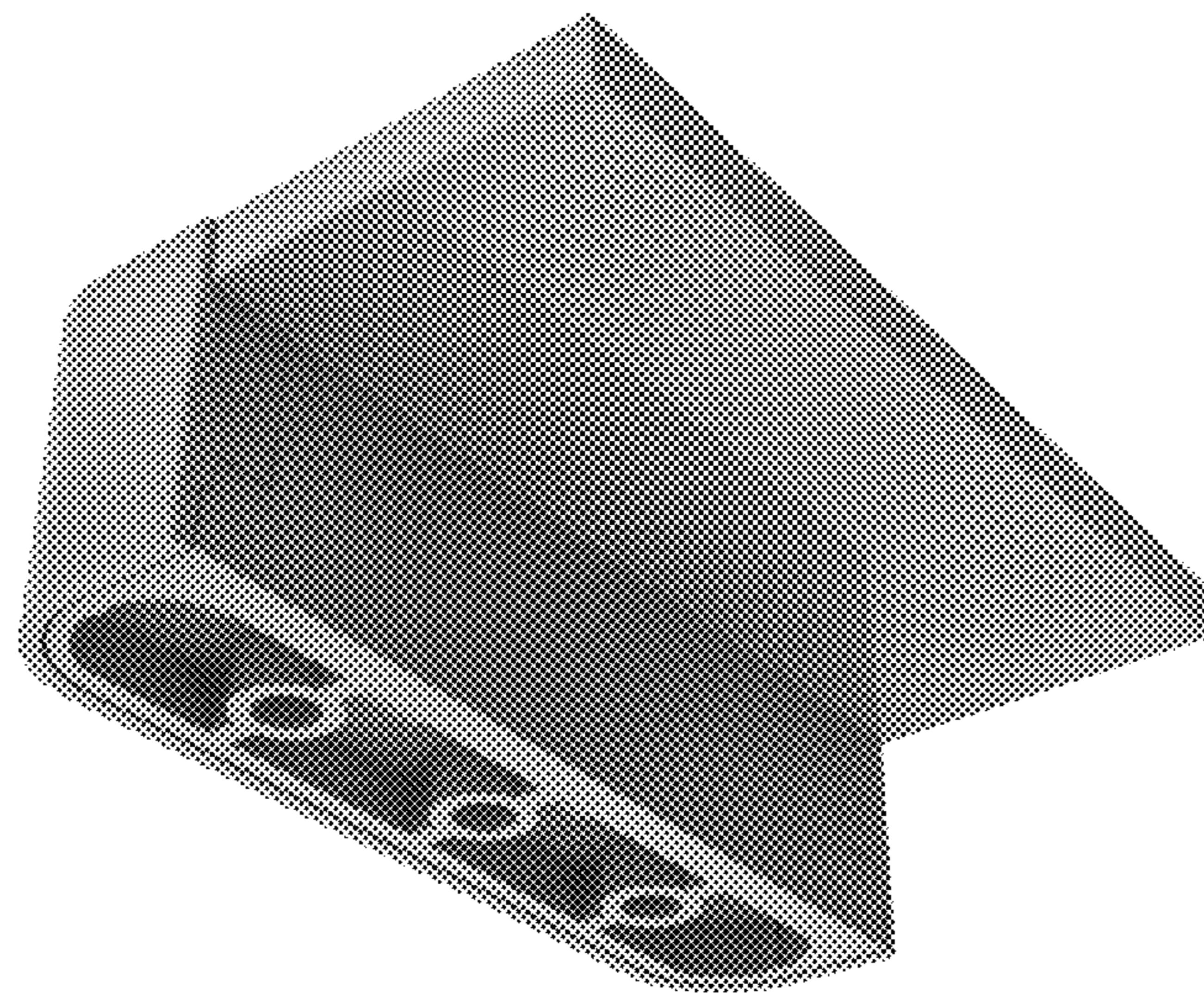


FIG. 8